

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Chun Hung LIN

Serial No. 09/854,487

Filed: May 15, 2001

For: LOW-PIN-COUNT CHIP PACKAGE HAVING CONCAVE DIE PAD AND/OR CONNECTIONS PADS (As Amended)

COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

☒ No additional fee is required.☐ Small entity status of this application has been established.☐ A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	14	20	0	x \$ 18 =	\$ 0.00
Independent Claims	2	3	0	x \$ 84 =	\$ 0.00
If multiple claims newly presented, add \$260.00					\$0.00
Fee for extension of time					\$0.00
TOTAL FEE DUE					\$ 0.00

☐ A check in the amount of \$0.00 is attached☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 07-1337, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

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Docket No.: 4459-018A

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PATENT

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In re Application of

Chun Hung LIN

Serial No. 09/854,487

Filed: May 15, 2001

Group Art Unit: 2826

Examiner: A. Williams

For: LOW-PIN-COUNT CHIP PACKAGE HAVING CONCAVE DIE PAD AND/OR CONNECTIONS PADS (as amended)

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AMENDMENT

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

Sir:

The following amendments and remarks are submitted in response to the Official Action dated December 18, 2002.

IN THE TITLE:

Please amend the Title as follows:

-- LOW-PIN-COUNT CHIP PACKAGE

HAVING CONCAVE DIE PAD AND/OR CONNECTIONS PADS --

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 7, line 10 with the following:

Referring to Fig. 7, a photoresist layer 350 is formed on a copper foil 235 by conventional techniques such as printing. Then, the photoresist layer 250 is photochemically defined through a photomask (not shown) and developed to expose predetermined portions of the copper foil 235. The photoresist layer 250 is mainly composed of a resin mixture and a photoactive material that

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